

CIRRUS LOGIC Process Change Notification

PCN Number: PCN-2015-20

PCN Notification Date: 05/26/2015

Informational

Lead Frame Vendor Change for CS1501-FSZ(R) and CS1601-FSZ(R)

Dear Customer,

This notification is to advise you of the following change(s).

Change of Lead Frame Supplier Source that supports our CS1501-FSZ(R) and CS1601-FSZ(R) component materials. The current Lead Frame Supplier Source experienced a fire in their factory, resulting in irreparable damage. To ensure continuity of supply, an alternate Lead Frame Supplier was qualified.

If you have any questions, please contact your Sales Representative.

Sincerely,

Quality Systems Administrator Cirrus Logic Corporate Quality Phone: +1(512) 851-4000



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Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

| Title: | | Lead Frame Vendor Change for CS1501-FSZ(R) and CS1601-FSZ(R) | | | | | | | |
|-------------------------------------|---------------------------|--|--------------------------|--------------------------|--------------------|-------|---------------------------|-------------------|--|
| Customer Contact: Local Field Sales | | | s Representative | | Phone: (512) 851-4 | 000 | Dept: | Corporate Quality | |
| Proposed 1 st Ship Date: | | | 06 2015 Estimated Sample | | | Avail | vailability Date: 05 2015 | | |
| Change Type: | | | | | | | | | |
| | Assembly Site | | | Assembly Process | | | Assembly Materials | | |
| | Wafer Fab Site | | | Wafer Fab Process | | | Wafer Fab Materials | | |
| | Wafer Bump Site | | | Wafer Bump Process | | | Wafer Bump Material | | |
| | Test Site | | | Test Process | | | Design | | |
| | Electrical Specification | | | Mechanical Specification | | | Part Number | | |
| | Packing/Shipping/Labeling | | Х | Other | | | | | |
| Con | Comments: Lead Frame Vend | | | hange | | | | | |

PCN Details

Description of Change:

Establish a qualified Lead Frame Supplier source to support the CS1501FSZ(R) and CS1601-FSZ(R) component material.

- No material content change
- No plating material change
- No dimensional change

Reason for Change:

The existing suppliers' facility suffered irreparable damage to their plating process.

Anticipated Impact on Form, Fit, Function, Quality or Reliability:

No anticipated adverse impact to the quality and/or reliability of said product.

Product Affected:

| Device | Cirrus Logic Part Number | Customer Part Number |
|--------|--------------------------|----------------------|
| 1 | CS1501-FSZ | |
| 2 | CS1501-FSZR | |
| 3 | CS1601-FSZ | |
| 4 | CS1601-FSZR | |

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Changes To Product Identification Resulting From This PCN:

No Change to the Product Identification

Qualification Data:

| This qualification has been speci qualification data validates that t specifications. | | | | |
|---|--------|---------|------|---------|
| Qualification Schedule | Start: | 03 2015 | End: | 06 2015 |



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The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

CS1501-FSZ Qualification

| Reliability Test | Standard | Conditions | Sample Size (PASS/FAIL) |
|--|----------------------------|--|----------------------------|
| | | 1 | |
| Pre-Conditioning | JEDEC J-STD-020A | MSL2 / 260°C (1 Lot) | 176 / # |
| Temperature Cycle | JESD22 A104 | -65°C to +150°C for 500 cycles (1 Lot) | 88 / # |
| WBS (Wire Bond Shear) | JESD22 B116 | Paragraph 4 (Procedure) (1 Lots 5 units 30 bonds) | 5 / # |
| WBP (Wire Bond Pull) | MIL-STD-883 Method 2011 | Paragraph 3 (Procedure) (1 Lots 5 units 30 bonds) | 5 / # |
| SD (Solderability) | JESD22 B102 | 93°C / 8 hr steam age before SD (1 Lot) | 30 / # |
| PD (Physical Dimensions) | JESD22 B100 + B108 | Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lot) | 10 / # |
| HTSL (High Temperature Storage Life) | JESD22 A103 | 150°C for 1000 hrs. (1 Lots) | 88 / # |

Notes:

- Qualification tests "pass" on zero fails for each test
- CS1501-FSZ serves as the Qualification Vehicle for CS1601-FSZ

Reliability Qualification Results:

TBD